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"<u>Embedded - Microcontrollers</u>" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "**<u>Embedded - Microcontrollers</u>**"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	14-SOIC (0.154", 3.90mm Width)
Supplier Device Package	14-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1704t-i-sl

PIC16(L)F1704/8

3.3 Data Memory Organization

The data memory is partitioned in 32 memory banks with 128 bytes in a bank. Each bank consists of (Figure 3-2):

- 12 core registers
- 20 Special Function Registers (SFR)
- Up to 80 bytes of General Purpose RAM (GPR)
- 16 bytes of common RAM

The active bank is selected by writing the bank number into the Bank Select Register (BSR). Unimplemented memory will read as '0'. All data memory can be accessed either directly (via instructions that use the file registers) or indirectly via the two File Select Registers (FSR). See **Section 3.7 "Indirect Addressing"** for more information.

Data memory uses a 12-bit address. The upper five bits of the address define the Bank address and the lower seven bits select the registers/RAM in that bank.

3.3.1 CORE REGISTERS

The core registers contain the registers that directly affect the basic operation. The core registers occupy the first 12 addresses of every data memory bank (addresses x00h/x08h through x0Bh/x8Bh). These registers are listed below in Table 3-2. For detailed information, see Table 3-9.

TABLE 3-2: CORE REGISTERS

Addresses	BANKx
x00h or x80h	INDF0
x01h or x81h	INDF1
x02h or x82h	PCL
x03h or x83h	STATUS
x04h or x84h	FSR0L
x05h or x85h	FSR0H
x06h or x86h	FSR1L
x07h or x87h	FSR1H
x08h or x88h	BSR
x09h or x89h	WREG
x0Ah or x8Ah	PCLATH
x0Bh or x8Bh	INTCON

3.3.1.1 STATUS Register

The STATUS register, shown in Register 3-1, contains:

- the arithmetic status of the ALU
- the Reset status

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper three bits and set the Z bit. This leaves the STATUS register as '000u uluu' (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register, because these instructions do not affect any Status bits. For other instructions not affecting any Status bits (Refer to **Section 31.0 "Instruction Set Summary"**).

Note:	The C and DC bits operate as $\overline{\text{Borrow}}$ and $\overline{\text{Digit Borrow}}$ out bits, respectively, in subtraction.

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5.13 Power Control (PCON) Register

The Power Control (PCON) register contains flag bits to differentiate between a:

- Power-on Reset ($\overline{POR}$)
- Brown-out Reset ($\overline{BOR}$)
- Reset Instruction Reset ($\overline{RI}$)
- $\overline{MCLR}$ Reset ($\overline{RMCLR}$)
- Watchdog Timer Reset ($\overline{RWDT}$)
- Stack Underflow Reset (STKUNF)
- Stack Overflow Reset (STKOVF)

The PCON register bits are shown in Register 5-2.

5.14 Register Definitions: Power Control

REGISTER 5-2: PCON: POWER CONTROL REGISTER

R/W/HS-0/q	R/W/HS-0/q	U-0	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-q/u	R/W/HC-q/u
STKOVF	STKUNF	—	$\overline{RWDT}$	$\overline{RMCLR}$	$\overline{RI}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:		
HC = Bit is cleared by hardware		HS = Bit is set by hardware
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7 **STKOVF:** Stack Overflow Flag bit

    1 = A Stack Overflow occurred
    0 = A Stack Overflow has not occurred or cleared by firmware

bit 6 **STKUNF:** Stack Underflow Flag bit

    1 = A Stack Underflow occurred
    0 = A Stack Underflow has not occurred or cleared by firmware

bit 5 **Unimplemented:** Read as '0'

bit 4 **$\overline{RWDT}$:** Watchdog Timer Reset Flag bit

    1 = A Watchdog Timer Reset has not occurred or set to '1' by firmware
    0 = A Watchdog Timer Reset has occurred (cleared by hardware)

bit 3 **$\overline{RMCLR}$:** $\overline{MCLR}$ Reset Flag bit

    1 = A $\overline{MCLR}$ Reset has not occurred or set to '1' by firmware
    0 = A $\overline{MCLR}$ Reset has occurred (cleared by hardware)

bit 2 **$\overline{RI}$:** RESET Instruction Flag bit

    1 = A RESET instruction has not been executed or set to '1' by firmware
    0 = A RESET instruction has been executed (cleared by hardware)

bit 1 **$\overline{POR}$:** Power-on Reset Status bit

    1 = No Power-on Reset occurred
    0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-out Reset Status bit

    1 = No Brown-out Reset occurred
    0 = A Brown-out Reset occurred (must be set in software after a Power-on Reset or Brown-out Reset occurs)

6.0 OSCILLATOR MODULE (WITH FAIL-SAFE CLOCK MONITOR)

6.1 Overview

The oscillator module has a wide variety of clock sources and selection features that allow it to be used in a wide range of applications while maximizing performance and minimizing power consumption. Figure 6-1 illustrates a block diagram of the oscillator module.

Clock sources can be supplied from external oscillators, quartz crystal resonators, ceramic resonators and Resistor-Capacitor (RC) circuits. In addition, the system clock source can be supplied from one of two internal oscillators and PLL circuits, with a choice of speeds selectable via software. Additional clock features include:

- Selectable system clock source between external or internal sources via software.
- Two-Speed Start-up mode, which minimizes latency between external oscillator start-up and code execution.
- Fail-Safe Clock Monitor (FSCM) designed to detect a failure of the external clock source (LP, XT, HS, ECH, ECM, ECL or EXTRC modes) and switch automatically to the internal oscillator.
- Oscillator Start-up Timer (OST) ensures stability of crystal oscillator sources.

The oscillator module can be configured in one of the following clock modes.

1. ECL – External Clock Low-Power mode (0 MHz to 0.5 MHz)
2. ECM – External Clock Medium Power mode (0.5 MHz to 4 MHz)
3. ECH – External Clock High-Power mode (4 MHz to 32 MHz)
4. LP – 32 kHz Low-Power Crystal mode.
5. XT – Medium Gain Crystal or Ceramic Resonator Oscillator mode (up to 4 MHz)
6. HS – High Gain Crystal or Ceramic Resonator mode (4 MHz to 20 MHz)
7. EXTRC – External Resistor-Capacitor
8. INTOSC – Internal oscillator (31 kHz to 32 MHz)

Clock Source modes are selected by the FOSC<2:0> bits in the Configuration Words. The FOSC bits determine the type of oscillator that will be used when the device is first powered.

The ECH, ECM, and ECL clock modes rely on an external logic level signal as the device clock source. The LP, XT, and HS clock modes require an external crystal or resonator to be connected to the device. Each mode is optimized for a different frequency range. The EXTRC clock mode requires an external resistor and capacitor to set the oscillator frequency.

The INTOSC internal oscillator block produces low, medium, and high-frequency clock sources, designated LFINTOSC, MFINTOSC and HFINTOSC. (see Internal Oscillator Block, Figure 6-1). A wide selection of device clock frequencies may be derived from these three clock sources.

REGISTER 6-2: **OSCSTAT: OSCILLATOR STATUS REGISTER**

R-1/q	R-0/q	R-q/q	R-0/q	R-0/q	R-q/q	R-0/0	R-0/q
SOSCR	PLLR	OSTS	HFIOFR	HFIOFL	MFIOFR	LFIOFR	HFIOFS
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Conditional

bit 7   **SOSCR:** Secondary Oscillator Ready bit

If T1OSCEN = 1:
1 = Secondary oscillator is ready
0 = Secondary oscillator is not ready
If T1OSCEN = 0:
1 = Secondary clock source is always ready

bit 6   **PLLR** 4x PLL Ready bit
1 = 4x PLL is ready
0 = 4x PLL is not ready

bit 5   **OSTS:** Oscillator Start-up Timer Status bit

1 = Running from the clock defined by the FOSC<2:0> bits of the Configuration Words
0 = Running from an internal oscillator (FOSC<2:0> = 100)

bit 4   **HFIOFR:** High-Frequency Internal Oscillator Ready bit

1 = HFINTOSC is ready
0 = HFINTOSC is not ready

bit 3   **HFIOFL:** High-Frequency Internal Oscillator Locked bit

1 = HFINTOSC is at least 2% accurate
0 = HFINTOSC is not 2% accurate

bit 2   **MFIOFR:** Medium-Frequency Internal Oscillator Ready bit

1 = MFINTOSC is ready
0 = MFINTOSC is not ready

bit 1   **LFIOFR:** Low-Frequency Internal Oscillator Ready bit

1 = LFINTOSC is ready
0 = LFINTOSC is not ready

bit 0   **HFIOFS:** High-Frequency Internal Oscillator Stable bit

1 = HFINTOSC is at least 0.5% accurate
0 = HFINTOSC is not 0.5% accurate

8.2 Low-Power Sleep Mode

The PIC16F1704/8 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. The PIC16F1704/8 allows the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

8.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

8.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The Low-Power Sleep mode is intended for use only with the following peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source<100 kHz)

Note:	The PIC16LF1704/8 does not have a configurable Low-Power Sleep mode. PIC16LF1704/8 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum V_{DD} and I/O voltage than the PIC16F1704/8. See **Section 32.0 "Electrical Specifications"** for more information.

EXAMPLE 10-2: **ERASING ONE ROW OF PROGRAM MEMORY**

```
; This row erase routine assumes the following:
; 1. A valid address within the erase row is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F (common RAM)


        BCF       INTCON,GIE    ; Disable ints so required sequences will execute properly
        BANKSEL   PMADRL
        MOVF      ADDRL,W       ; Load lower 8 bits of erase address boundary
        MOVWF     PMADRL
        MOVF      ADDRH,W       ; Load upper 6 bits of erase address boundary
        MOVWF     PMADRH
        BCF       PMCON1,CFGS   ; Not configuration space
        BSF       PMCON1,FREE   ; Specify an erase operation
        BSF       PMCON1,WREN   ; Enable writes

        MOVLW     55h           ; Start of required sequence to initiate erase
        MOVWF     PMCON2        ; Write 55h
        MOVLW     0AAh          ;
        MOVWF     PMCON2        ; Write AAh
        BSF       PMCON1,WR     ; Set WR bit to begin erase
        NOP                     ; NOP instructions are forced as processor starts
        NOP                     ; row erase of program memory.
                                ;
                                ; The processor stalls until the erase process is complete
                                ; after erase processor continues with 3rd instruction

        BCF       PMCON1,WREN   ; Disable writes
        BSF       INTCON,GIE    ; Enable interrupts
```

(Required Sequence: MOVLW 55h through NOP instructions)

11.1.7 PORTA FUNCTIONS AND OUTPUT PRIORITIES

Each PORTA pin is multiplexed with other functions.

Each pin defaults to the PORT latch data after Reset. Other functions are selected with the peripheral pin select logic. See **Section 12.0 "Peripheral Pin Select (PPS) Module"** for more information.

Analog input functions, such as ADC and comparator inputs are not shown in the peripheral pin select lists. These inputs are active when the I/O pin is set for Analog mode using the ANSELA register. Digital output functions may continue to control the pin when it is in Analog mode.

11.3 PORTB Registers (PIC16(L)F1708 only)

PORTB is a 4-bit wide, bidirectional port. The corresponding data direction register is TRISB (Register 11-10). Setting a TRISB bit (= 1) will make the corresponding PORTB pin an input (i.e., put the corresponding output driver in a High-Impedance mode). Clearing a TRISB bit (= 0) will make the corresponding PORTB pin an output (i.e., enable the output driver and put the contents of the output latch on the selected pin). Example 11-1 shows how to initialize an I/O port.

Reading the PORTB register (Register 11-9) reads the status of the pins, whereas writing to it will write to the PORT latch. All write operations are read-modify-write operations. Therefore, a write to a port implies that the port pins are read, this value is modified and then written to the PORT data latch (LATB).

11.3.1 DIRECTION CONTROL

The TRISB register (Register 11-10) controls the PORTB pin output drivers, even when they are being used as analog inputs. The user should ensure the bits in the TRISB register are maintained set when using them as analog inputs. I/O pins configured as analog inputs always read '0'.

11.3.2 OPEN-DRAIN CONTROL

The ODCONB register (Register 11-14) controls the open-drain feature of the port. Open-drain operation is independently selected for each pin. When an ODCONB bit is set, the corresponding port output becomes an open-drain driver capable of sinking current only. When an ODCONB bit is cleared, the corresponding port output pin is the standard push-pull drive capable of sourcing and sinking current.

11.3.3 SLEW RATE CONTROL

The SLRCONB register (Register 11-15) controls the slew rate option for each port pin. Slew rate control is independently selectable for each port pin. When an SLRCONB bit is set, the corresponding port pin drive is slew rate limited. When an SLRCONB bit is cleared, The corresponding port pin drive slews at the maximum rate possible.

11.3.4 INPUT THRESHOLD CONTROL

The INLVLB register (Register 11-16) controls the input voltage threshold for each of the available PORTB input pins. A selection between the Schmitt Trigger CMOS or the TTL Compatible thresholds is available. The input threshold is important in determining the value of a read of the PORTB register and also the level at which an interrupt-on-change occurs, if that feature is enabled. See Table 32-4: I/O Ports for more information on threshold levels.

| Note: | Changing the input threshold selection should be performed while all peripheral modules are disabled. Changing the threshold level during the time a module is active may inadvertently generate a transition associated with an input pin, regardless of the actual voltage level on that pin. |

11.3.5 ANALOG CONTROL

The ANSELB register (Register 11-12) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELB bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELB bits has no effect on digital output functions. A pin with TRIS clear and ANSELB set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

| Note: | The ANSELB bits default to the Analog mode after Reset. To use any pins as digital general purpose or peripheral inputs, the corresponding ANSEL bits must be initialized to '0' by user software. |

11.3.6 PORTB FUNCTIONS AND OUTPUT PRIORITIES

Each pin defaults to the PORT latch data after reset. Other functions are selected with the peripheral pin select logic. See **Section 12.0 "Peripheral Pin Select (PPS) Module"** for more information. Analog input functions, such as ADC and Op Amp inputs, are not shown in the peripheral pin select lists. These inputs are active when the I/O pin is set for Analog mode using the ANSELB register. Digital output functions may continue to control the pin when it is in Analog mode.

18.5.4 RISING EVENT DEAD-BAND

Rising event dead band delays the turn-on of the primary outputs from when complementary outputs are turned off. The rising event dead-band time starts when the rising_ event output goes true.

See Section 18.5.1, Asynchronous delay chain dead-band delay and Section 18.5.2, Synchronous counter dead-band delay for more information on setting the rising edge dead-band time.

18.5.5 FALLING EVENT DEAD-BAND

Falling event dead band delays the turn-on of complementary outputs from when the primary outputs are turned off. The falling event dead-band time starts when the falling_ event output goes true.

See Section 18.5.1, Asynchronous delay chain dead-band delay and Section 18.5.2, Synchronous counter dead-band delay for more information on setting the rising edge dead-band time.

18.5.6 DEAD-BAND OVERLAP

There are two cases of dead-band overlap:
• Rising-to-falling
• Falling-to-rising

18.5.6.1 Rising-to-Falling Overlap

In this case, the falling event occurs while the rising event dead-band counter is still counting. When this happens, the primary drives are suppressed and the dead-band extends by the falling event dead-band time. At the termination of the extended dead-band time, the complementary drive goes true.

18.5.6.2 Falling-to-Rising Overlap

In this case, the rising event occurs while the falling event dead-band counter is still counting. When this happens, the complementary drive is suppressed and the dead-band extends by the rising event dead-band time. At the termination of the extended dead-band time, the primary drive goes true.

18.6 Blanking Control

Input blanking is a function, whereby, the event inputs can be masked or blanked for a short period of time. This is to prevent electrical transients caused by the turn-on/off of power components from generating a false input event.

The COG contains two blanking counters: one triggered by the rising event and the other triggered by the falling event. The counters are cross coupled with the events they are blanking. The falling event blanking counter is used to blank rising input events and the rising event blanking counter is used to blank falling input events. Once started, blanking extends for the time specified by the corresponding blanking counter.

Blanking is timed by counting COG_clock periods from zero up to the value in the blanking count register. Use Equation 18-1 to calculate blanking times.

18.6.1 FALLING EVENT BLANKING OF RISING EVENT INPUTS

The falling event blanking counter inhibits rising event inputs from triggering a rising event. The falling event blanking time starts when the rising event output drive goes false.

The falling event blanking time is set by the value contained in the COGxBLKF register (Register 18-13). Blanking times are calculated using the formula shown in Equation 18-1.

When the COGxBLKF value is zero, falling event blanking is disabled and the blanking counter output is true, thereby, allowing the event signal to pass straight through to the event trigger circuit.

18.6.2 RISING EVENT BLANKING OF FALLING EVENT INPUTS

The rising event blanking counter inhibits falling event inputs from triggering a falling event. The rising event blanking time starts when the falling event output drive goes false.

The rising event blanking time is set by the value contained in the COGxBLKR register (Register 18-12).

When the COGxBLKR value is zero, rising event blanking is disabled and the blanking counter output is true, thereby, allowing the event signal to pass straight through to the event trigger circuit.

18.6.3 BLANKING TIME UNCERTAINTY

When the rising and falling sources that trigger the blanking counters are asynchronous to the COG_clock, it creates uncertainty in the blanking time. The maximum uncertainty is equal to one COG_clock period. Refer to Equation 18-1 and Example 18-1 for more detail.

18.7 Phase Delay

It is possible to delay the assertion of either or both the rising event and falling events. This is accomplished by placing a non-zero value in COGxPHR or COGxPHF phase-delay count register, respectively (Register 18-14 and Register 18-15). Refer to Figure 18-10 for COG operation with CCP1 and phase delay. The delay from the input rising event signal switching to the actual assertion of the events is calculated the same as the dead-band and blanking delays. Refer to Equation 18-1.

REGISTER 18-8: COGxASD1: COG AUTO-SHUTDOWN CONTROL REGISTER 1

U-0	U-0	U-0	U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	—	—	—	GxAS3E	GxAS2E	GxAS1E	GxAS0E
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	q = Value depends on condition

bit 7-4   **Unimplemented:** Read as '0'

bit 3   **GxAS3E:** COGx Auto-shutdown Source Enable bit 3
   1 = COGx is shutdown when CLC2 output is low
   0 = CLC2 output has no effect on shutdown

bit 2   **GxAS2E:** COGx Auto-shutdown Source Enable bit 2
   1 = COGx is shutdown when Comparator 2 output is low
   0 = Comparator 2 output has no effect on shutdown

bit 1   **GxAS1E:** COGx Auto-shutdown Source Enable bit 1
   1 = COGx is shutdown when Comparator 1 output is low
   0 = Comparator 1 output has no effect on shutdown

bit 0   **GxAS0E:** COGx Auto-shutdown Source Enable bit 0
   1 = COGx is shutdown when Pin selected with COGxPPS control is low
   0 = Pin selected with COGxPPS control has no effect on shutdown

20.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC Interrupt Flag is the ADIF bit in the PIR1 register. The ADC Interrupt Enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note 1:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
2:	The ADC operates during Sleep only when the FRC oscillator is selected.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the ADIE bit of the PIE1 register and the PEIE bit of the INTCON register must both be set and the GIE bit of the INTCON register must be cleared. If all three of these bits are set, the execution will switch to the Interrupt Service Routine.

20.1.6 RESULT FORMATTING

The 10-bit ADC conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON1 register controls the output format.

Figure 20-3 shows the two output formats.

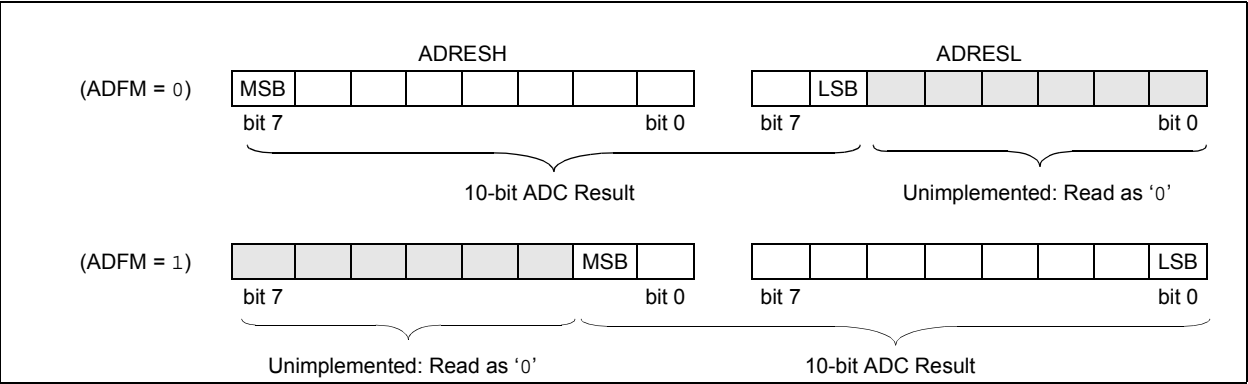**FIGURE 20-3: 10-BIT ADC CONVERSION RESULT FORMAT**

FIGURE 28-5: **SPI MASTER/SLAVE CONNECTION**
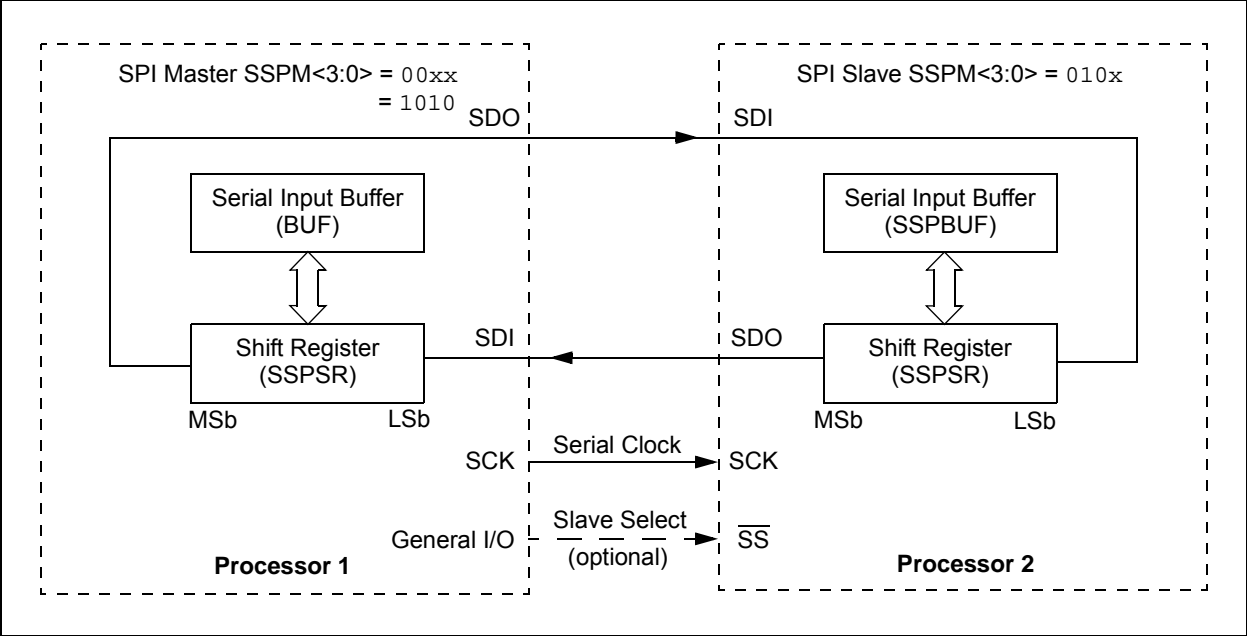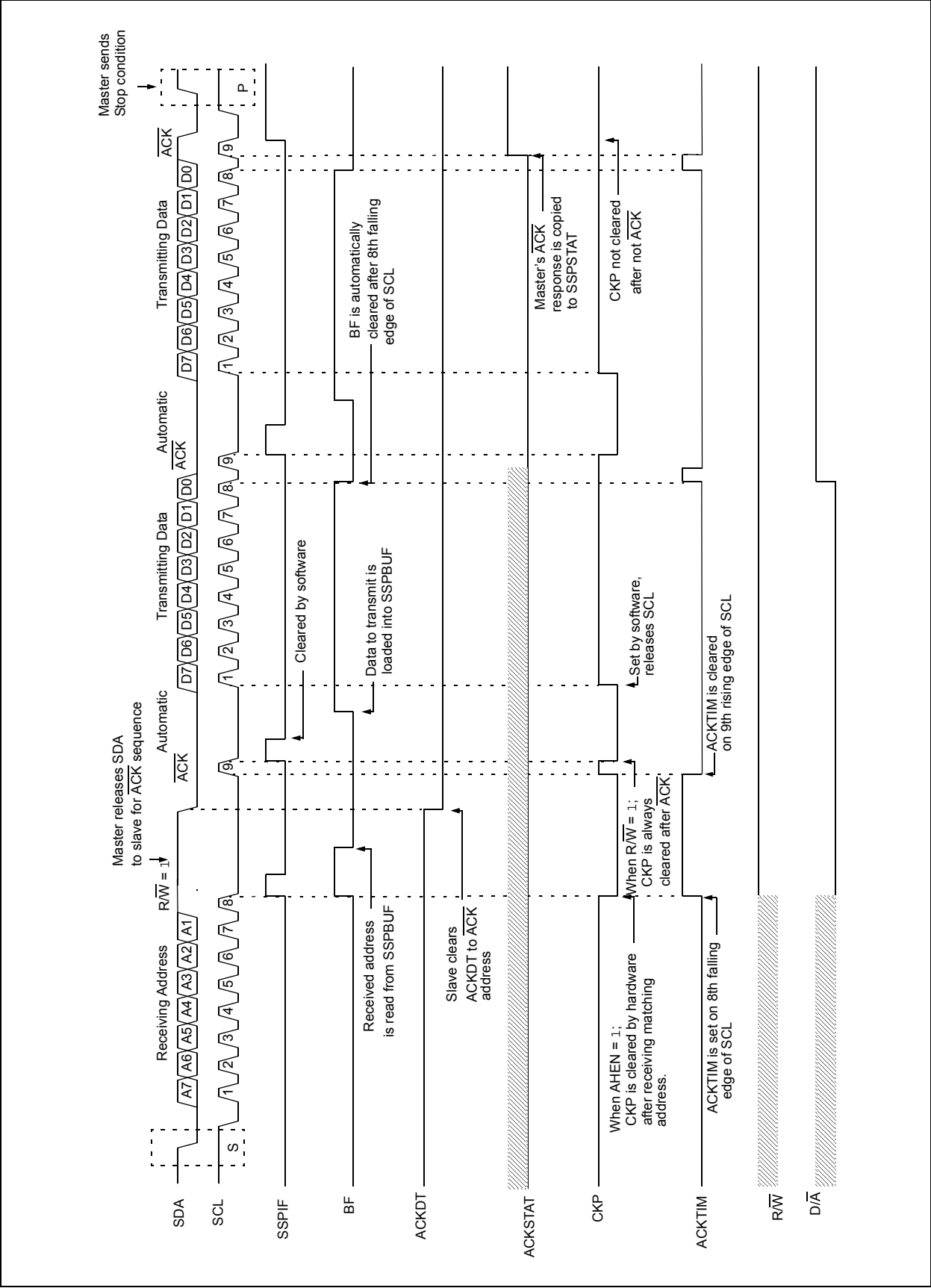
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FIGURE 28-19: I²C SLAVE, 7-BIT ADDRESS, TRANSMISSION (AHEN = 1)

28.8 Register Definitions: MSSP Control

REGISTER 28-1: SSP1STAT: SSP STATUS REGISTER

R/W-0/0	R/W-0/0	R-0/0	R-0/0	R-0/0	R-0/0	R-0/0	R-0/0
SMP	CKE	D/$\overline{\text{A}}$	P	S	R/$\overline{\text{W}}$	UA	BF
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **SMP:** SPI Data Input Sample bit

SPI Master mode:
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time

SPI Slave mode:
SMP must be cleared when SPI is used in Slave mode

In I^{2}C Master or Slave mode:
1 = Slew rate control disabled for Standard Speed mode (100 kHz and 1 MHz)
0 = Slew rate control enabled for High-Speed mode (400 kHz)

bit 6 **CKE:** SPI Clock Edge Select bit (SPI mode only)

In SPI Master or Slave mode:
1 = Transmit occurs on transition from active to Idle clock state
0 = Transmit occurs on transition from Idle to active clock state

In I^{2}C™ mode only:
1 = Enable input logic so that thresholds are compliant with SMBus specification
0 = Disable SMBus specific inputs

bit 5 **D/$\overline{\text{A}}$:** Data/$\overline{\text{Address}}$ bit (I^{2}C mode only)
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4 **P:** Stop bit
(I^{2}C mode only. This bit is cleared when the MSSP module is disabled, SSPEN is cleared.)
1 = Indicates that a Stop bit has been detected last (this bit is '0' on Reset)
0 = Stop bit was not detected last

bit 3 **S:** Start bit
(I^{2}C mode only. This bit is cleared when the MSSP module is disabled, SSPEN is cleared.)
1 = Indicates that a Start bit has been detected last (this bit is '0' on Reset)
0 = Start bit was not detected last

bit 2 **R/$\overline{\text{W}}$:** Read/$\overline{\text{Write}}$ bit information (I^{2}C mode only)
This bit holds the R/$\overline{\text{W}}$ bit information following the last address match. This bit is only valid from the address match to the next Start bit, Stop bit, or not ACK bit.
In I^{2}C Slave mode:
1 = Read
0 = Write
In I^{2}C Master mode:
1 = Transmit is in progress
0 = Transmit is not in progress
OR-ing this bit with SEN, RSEN, PEN, RCEN or ACKEN will indicate if the MSSP is in Idle mode.

bit 1 **UA:** Update Address bit (10-bit I^{2}C mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

29.4 EUSART Baud Rate Generator (BRG)

The Baud Rate Generator (BRG) is an 8-bit or 16-bit timer that is dedicated to the support of both the asynchronous and synchronous EUSART operation. By default, the BRG operates in 8-bit mode. Setting the BRG16 bit of the BAUDCON register selects 16-bit mode.

The SPBRGH, SPBRGL register pair determines the period of the free running baud rate timer. In Asynchronous mode the multiplier of the baud rate period is determined by both the BRGH bit of the TXSTA register and the BRG16 bit of the BAUDCON register. In Synchronous mode, the BRGH bit is ignored.

Table 29-3 contains the formulas for determining the baud rate. Example 29-1 provides a sample calculation for determining the baud rate and baud rate error.

Typical baud rates and error values for various asynchronous modes have been computed for your convenience and are shown in Table 29-5. It may be advantageous to use the high baud rate (BRGH = `1`), or the 16-bit BRG (BRG16 = `1`) to reduce the baud rate error. The 16-bit BRG mode is used to achieve slow baud rates for fast oscillator frequencies.

Writing a new value to the SPBRGH, SPBRGL register pair causes the BRG timer to be reset (or cleared). This ensures that the BRG does not wait for a timer overflow before outputting the new baud rate.

If the system clock is changed during an active receive operation, a receive error or data loss may result. To avoid this problem, check the status of the RCIDL bit to make sure that the receive operation is idle before changing the system clock.

EXAMPLE 29-1: CALCULATING BAUD RATE ERROR

For a device with F_{OSC} of 16 MHz, desired baud rate of 9600, Asynchronous mode, 8-bit BRG:

$$Desired\ Baud\ Rate\ = \frac{F_{OSC}}{64([SPBRGH:SPBRGL] + 1)}$$

Solving for SPBRGH:SPBRGL:

$$X = \frac{\frac{F_{OSC}}{Desired\ Baud\ Rate}}{64} - 1$$

$$= \frac{\frac{16000000}{9600}}{64} - 1$$

$$= [25.042] = 25$$

$$Calculated\ Baud\ Rate\ = \frac{16000000}{64(25 + 1)}$$

$$= 9615$$

$$Error = \frac{Calc.\ Baud\ Rate - Desired\ Baud\ Rate}{Desired\ Baud\ Rate}$$

$$= \frac{(9615 - 9600)}{9600} = 0.16\%$$

TABLE 31-3: PIC16(L)F1704/8 INSTRUCTION SET

Mnemonic, Operands		Description	Cycles	14-Bit Opcode MSb			LSb	Status Affected	Notes
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C, DC, Z	2
ADDWFC	f, d	Add with Carry W and f	1	11	1101	dfff	ffff	C, DC, Z	2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	2
ASRF	f, d	Arithmetic Right Shift	1	11	0111	dfff	ffff	C, Z	2
LSLF	f, d	Logical Left Shift	1	11	0101	dfff	ffff	C, Z	2
LSRF	f, d	Logical Right Shift	1	11	0110	dfff	ffff	C, Z	2
CLRF	f	Clear f	1	00	0001	1fff	ffff	Z	2
CLRW	–	Clear W	1	00	0001	0000	00xx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	2
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	2
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	2
MOVWF	f	Move W to f	1	00	0000	1fff	ffff		2
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C, DC, Z	2
SUBWFB	f, d	Subtract with Borrow W from f	1	11	1011	dfff	ffff	C, DC, Z	2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	2
BYTE ORIENTED SKIP OPERATIONS									
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1, 2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1, 2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		2
BIT-ORIENTED SKIP OPERATIONS									
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		1, 2
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		1, 2
LITERAL OPERATIONS									
ADDLW	k	Add literal and W	1	11	1110	kkkk	kkkk	C, DC, Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLB	k	Move literal to BSR	1	00	0000	001k	kkkk		
MOVLP	k	Move literal to PCLATH	1	11	0001	1kkk	kkkk		
MOVLW	k	Move literal to W	1	11	0000	kkkk	kkkk		
SUBLW	k	Subtract W from literal	1	11	1100	kkkk	kkkk	C, DC, Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

Note 1: If the Program Counter (PC) is modified, or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

2: If this instruction addresses an INDF register and the MSb of the corresponding FSR is set, this instruction will require one additional instruction cycle.

TABLE 32-15: ANALOG-TO-DIGITAL CONVERTER (ADC) CHARACTERISTICS[1,2]:

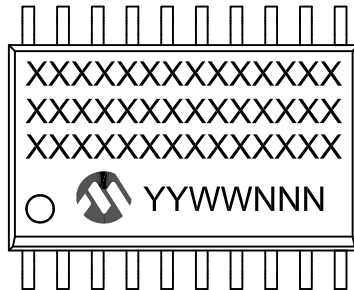| Param. No.	Sym.	Characteristic	Min.	Typ.†	Max.	Units	Conditions
		Standard Operating Conditions (unless otherwise stated) **Operating temperature: Tested at 25°C**					
AD01	N_R	Resolution	—	—	10	bit	
AD02	E_{IL}	Integral Error	—	—	±1.7	LSb	V_{REF} = 3.0V
AD03	E_{DL}	Differential Error	—	—	±1	LSb	No missing codes, V_{REF} = 3.0V
AD04	E_{OFF}	Offset Error	—	—	±2.5	LSb	V_{REF} = 3.0V
AD05	E_{GN}	Gain Error	—	—	±2.0	LSb	V_{REF} = 3.0V
AD06	V_{REF}	Reference Voltage[3]	1.8	—	V_{DD}	V	V_{REF} = (V_{REF}+ minus V_{REF}-)
AD07	V_{AIN}	Full-Scale Range	V_{SS}	—	V_{REF}	V	
AD08	Z_{AIN}	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	Can go higher if external 0.01 μF capacitor is present on input pin.

   * These parameters are characterized but not tested.

   † Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

    2: The ADC conversion result never decreases with an increase in the input voltage and has no missing codes.

    3: V_{REF} = (V_{REF}+ – V_{REF}-); ADCREF+ may be V_{DD}, V_{REF}+ pin or FVR1_buffer. The ADCREF- may be V_{SS} or V_{REF}- pin. If selecting the FVR1_buffer, the buffers output voltage must be 2.048V or 4.096V.

TABLE 32-16: ADC CONVERSION REQUIREMENTS

Param. No.	Sym.	Characteristic	Min.	Typ.†	Max.	Units	Conditions
		Standard Operating Conditions (unless otherwise stated)					
AD130*	T_{AD}	ADC Clock Period (T_{ADC})	1.0	—	9.0	μs	F_{OSC}-based
		FRC Oscillator Period (T_{FRC})	1.0	2	6.0	μs	ADCS<1:0> = 11 (ADC FRC mode)
AD131	T_{CNV}	Conversion Time (not including Acquisition Time)[1]	—	11	—	T_{AD}	Set GO/DONE bit to conversion complete
AD132*	T_{ACQ}	Acquisition Time	—	5.0	—	μs	
AD133*	T_{HCD}	Holding Capacitor Disconnect Time	—	0.5 T_{AD}	—		ADCS<2:0> ≠ x11 (F_{OSC} based)
			—	1/2 T_{AD} + 1 T_{CY}	—		ADCS<2:0> = x11 (FRC based)

   * These parameters are characterized but not tested.

   † Data in "Typ." column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
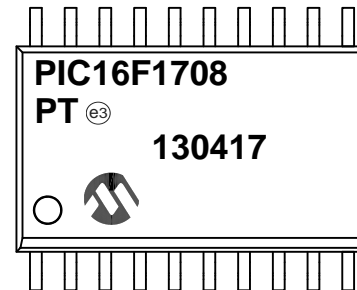
Note 1: The ADRES register may be read on the following T_{CY} cycle.
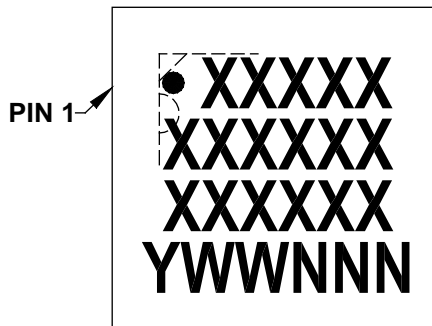
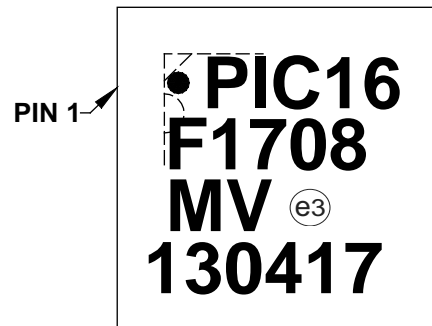## Package Marking Information (Continued)

20-Lead SOIC (7.50 mm)   Example

```
XXXXXXXXXXXXX
XXXXXXXXXXXXX
XXXXXXXXXXXXX
○  Ⓜ  YYWWNNN
```

```
PIC16F1708
PT ⓔ3
          130417
○  Ⓜ
```

20-Lead QFN (4x4x0.9 mm)   Example

PIN 1 →
```
●XXXXX
XXXXXX
XXXXXX
YWWNNN
```

PIN 1 →
```
●PIC16
F1708
MV ⓔ3
130417
```

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	ⓔ3	Pb-free JEDEC® designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC® designator (ⓔ3) can be found on the outer packaging for this package.

Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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